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DATA SHEET

PART NO. : B-1C2CHUR

REV : A / 0

CUSTOMER'S APPROVAL : _____

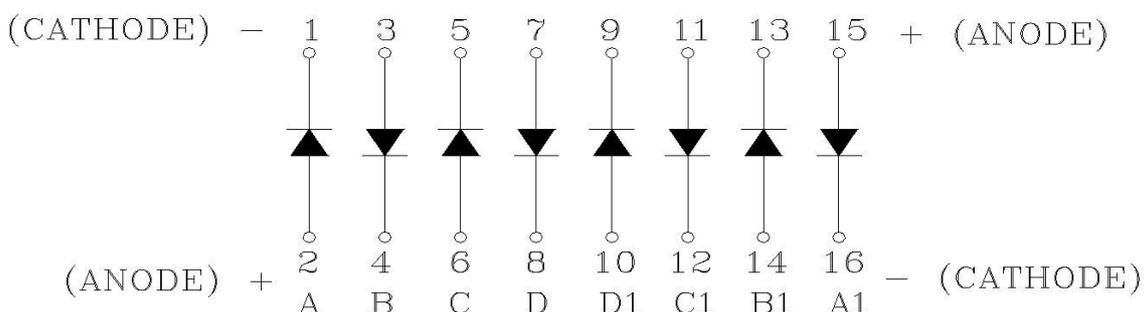
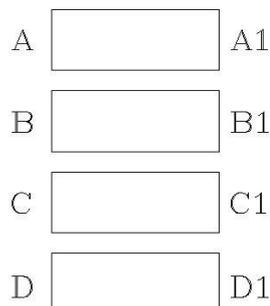
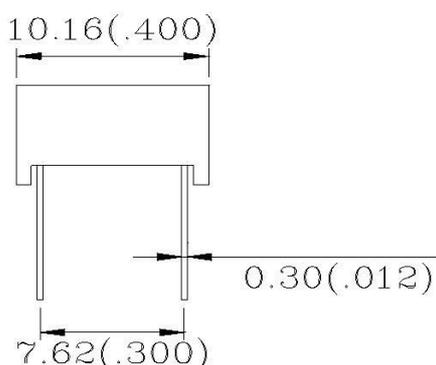
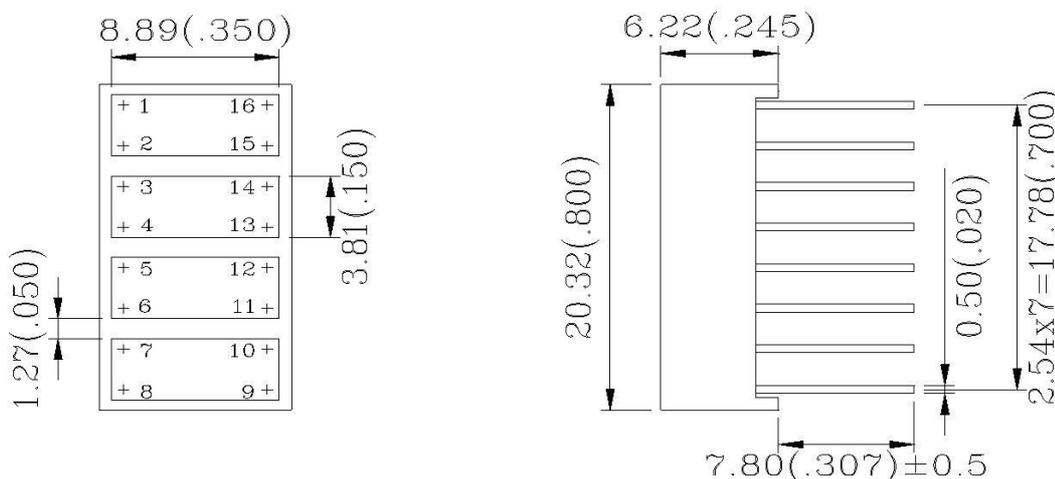
DCC : _____

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PACKAGE DIMENSIONS



NOTES : 1. All dimensions are in millimeters. (inches)
 2. Tolerance is $\pm 0.25(0.010)$ unless otherwise specified.



10.16mm x 20.32 mm SQUARE LIGHT BAR

B-1C2CHUR

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FEATURES

- 10.16mm x 20.32mm SQUARE LIGHT BAR
- LOW POWER REQUIREMENT
- CAN BE USED WITH PANEL AND LEGEND MOUNT
- SUITABLE FOR MULTIPLEX OPERATION
- EASY MOUNTING ON P.C.B
- WHITE SEGMENTS

Raw Material : GaAlInP/GaAs

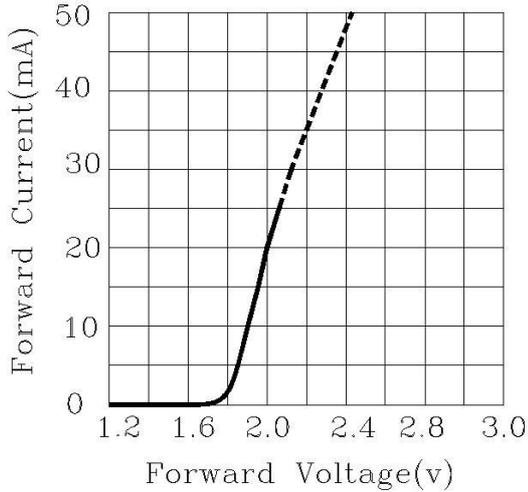
ABSOLUTE MAXIMUM RATING : (Ta = 25°C)

SYMBOL	PARAMETER	ULTRA RED	UNIT
PD	Power Dissipation Per Segment	60	mW
VR	Reverse Voltage Per Segment	5	V
IAF	Continuous Forward Current Per Segment	20	mA
IPF	Peak Forward Current Per Segment (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
—	Derating Linear From 25°C Per Segment	0.4	mA/°C
Topr	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	

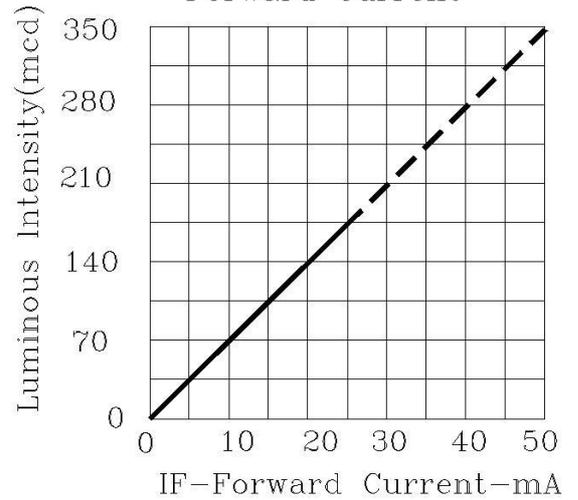
ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage , Per Chip	IF = 20mA		2.0	2.5	V
IR	Reverse Current , Per Chip	VR = 5V			100	µA
λP	Peak Emission Wavelength	IF = 20mA		638		nm
λD	Dominant Wavelength	IF = 20mA		628		nm
Δλ	Spectral Line Half—Width	IF = 20mA		20		nm
IV	Luminous Intensity Per Segment	IF = 10mA	28	70		mcd

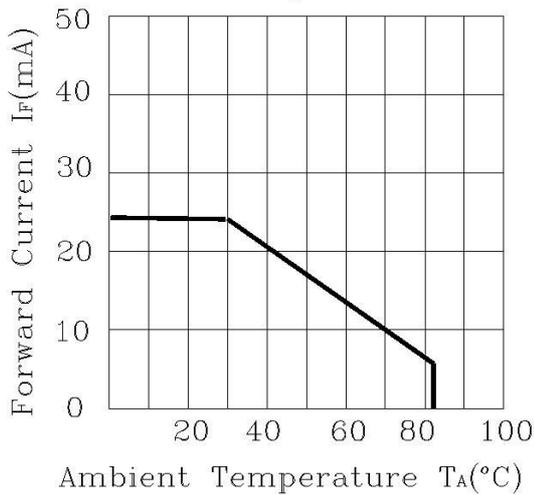
Forward Current Vs Forward Voltage



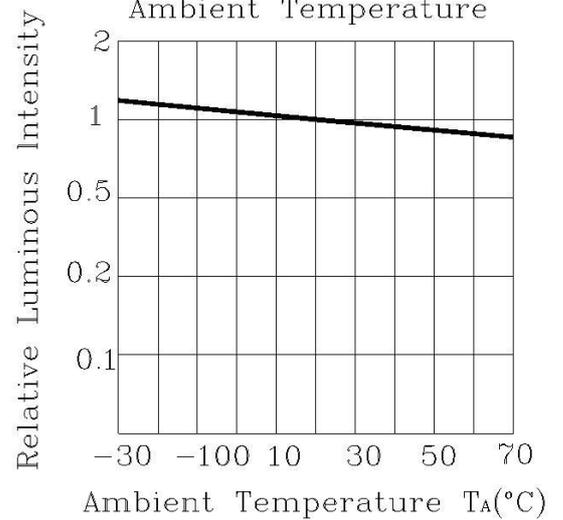
Luminous Intensity VS. Forward Current



Forward Current Derating Curve



Luminous Intensity VS. Ambient Temperature



10.16mm x 20.32 mm SQUARE LIGHT BAR

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SOLDERING METHOD		SOLDERING CONDITIONS	REMARK
DIP SOLDERING	Bath temperature: 260 max Immersion time: with 5 sec		Solder no closer than 2mm from the base of the package Using soldering flux, "RESIN FLUX" is recommended.
			During soldering, take care Temperature at tip of iron: 260°C or not to
SOLDERING			press the tip of iron against the PIN. lower Soldering iron: 30W or smaller

IRON

prevent heat from being Soldering time: within 3 sec.

(To

transferred directly to the PIN.)

- 1) When soldering the PIN of Display in a jig that the package is fixed with a panel (See fig.1), be careful not to stress the PIN with iron tip. When soldering Display in a condition that the package is fixed with a panel, be careful not to cling and stress the surface of Display on the panel to avoid damaging the Display.

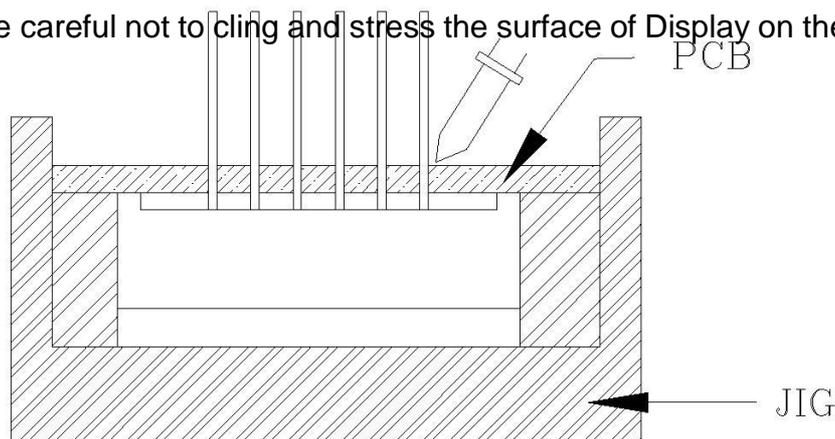


Fig.1

Regarding solution in the tinning oven for product-tinning, compound sub-solution made of tin & copper and silver is proposed with the temperature of Celsius 260. The proportion of the

alloyed solution is tin 95.5: copper 3.5: silver 0.5 by percentage. The time of tinning is constantly 3 seconds.

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